

Heat Dissipation Design



CLL130 Series

Heat dissipation design is a precondition in order to maximize the performance of the LED. In this document, the data that is deemed necessary in the detailed heat dissipation structure of the products and the heat dissipation design of the lighting apparatus is provided as a reference for the appropriate thermal design.

CONTENTS

| | |
|---|-----|
| 1. Introduction | P.2 |
| 2. Package structure and thermal resistance | P.2 |
| 3. Thermal design outside the package | P.3 |

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Heat dissipation structure that can conduct heat radiated from LEDs efficiently

1. Introduction

Significance of the heat dissipation structure

The light-emitting diode of an LED package radiates light and heat according to the input power. However, the surface area of an LED package is quite small, and the package itself is expected to release little heat into the atmosphere. An external radiator such as a heat sink is thus required. The heat dissipation structure up to the connection portion of the external radiator uses mainly heat conduction.

Regarding LED packages, to control the junction temperature of the light-emitting diode T_j is important. The T_j must be kept from exceeding the absolute maximum rating in the specifications under any conditions. As direct measurement of the junction temperature of a light-emitting diode inside a package is difficult, the temperature of a particular part on the

external package (the soldering temperature) T_s [°C] is normally measured. T_j [°C] is calculated using the thermal resistance between the junction and the case R_{j-s} [°C/W], and the emitted heat amount that is nearly equal to the input power P_d [W]. The heat generated at the light-emitting diode can be conducted to the external radiator efficiently because the package structure for the CLL130 series minimizes the thermal resistance R_{j-s} .

This document describes the detailed heat dissipation structure of the CLL130 series and provides data necessary for thermal design of the lighting apparatus to maximize LED performance.

2. Package structure and thermal resistance

Understanding the junction temperature

The cross-sectional structure example, where the package of the CLL130 series is connected to an external laminated circuit board, is shown in Figure-1 (a). The package has a laminated structure with a light-emitting diode mounted on a substrate, which has conductive copper foil patterns and through-holes. A distinctive point is to be able to conduct the heat generated at the light-emitting diode via through-holes to the outside of the package efficiently.

The electrode section of the package outer shell is connected via solder to the electrode on the external circuit board that doubles as the heat sink for conductive connection. As described above, the heat generated in the junction section of the light-emitting diode is transferred using heat conduction mainly to the electrode on the external circuit board, which doubles as the heat sink, through the light-emitting diode to adhesive for die-mounting to through-holes to the electrode of the outer shell to solder. The thermal resistance between

the junction section of the light-emitting diode and the electrode side of the outer shell is R_{j-s} and the specific thermal resistance value of the package.

Therefore, the following formula is used:

$$T_j = R_{j-s} \cdot P_d + T_s$$

In addition, the thermal resistance of the solder outside the package is R_s [°C/W], the thermal resistance of the electrodes with the heat sink function is R_e [°C/W], and the ambient temperature is T_a [°C].

Figure-2 (b) indicates the equivalent thermal resistance along the cross-sectional diagram in Figure-2 (a). As indicated, the thermal resistances R_{j-s} , R_s , and R_e are connected in series between the junction temperature T_j and the ambient temperature T_a . The thermal resistances outside the package R_s and R_e can be integrated into the thermal resistance R_{s-a} at this point. Thus, the following formula is also used:

$$T_j = (R_{j-s} + R_{s-a}) \cdot P_d + T_a$$

Figure-2 (a) Thermal Resistance Connection

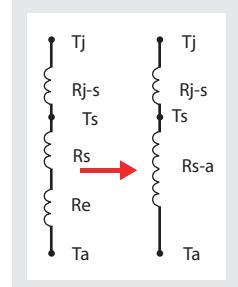
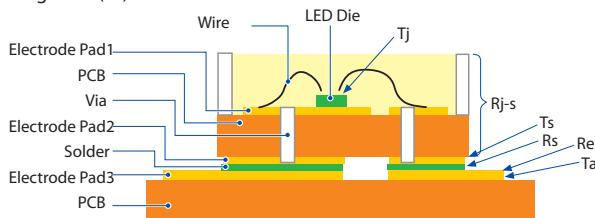


Figure-1 (a) Cross Section



Considering the design outside the package based on ambient temperature and driving parameters.

3. Thermal design on the outside of the package

Point of the external heat dissipation mechanism

The thermal resistance outside the package R_{s-a} [°C/W], which is the combination of the thermal resistance of the solder R_s [°C/W] and the thermal resistance of the electrodes with the heat sink function R_e [°C/W], is limited by the input power P_d [W], the ambient temperature T_a [°C], and the thermal resistance of the package R_{j-s} [°C/W], i.e.,

$$T_j = (R_{j-s} + R_{s-a}) \cdot P_d + T_a \quad \rightarrow R_{s-a} = (T_j - T_a) / P_d - R_{j-s}$$

T_j function converted from the above formula is

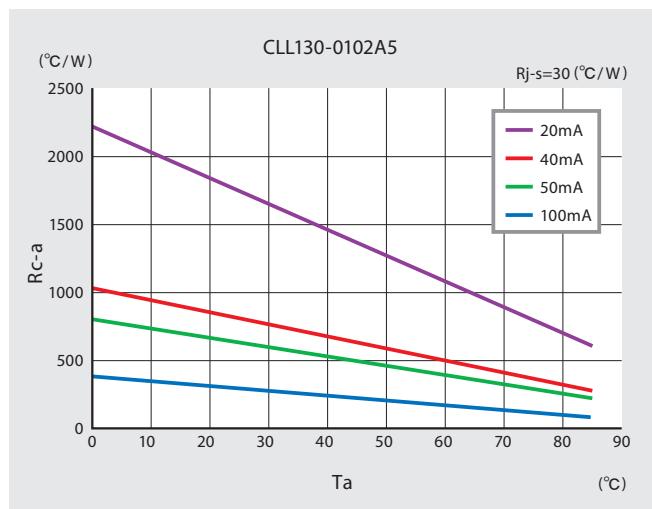
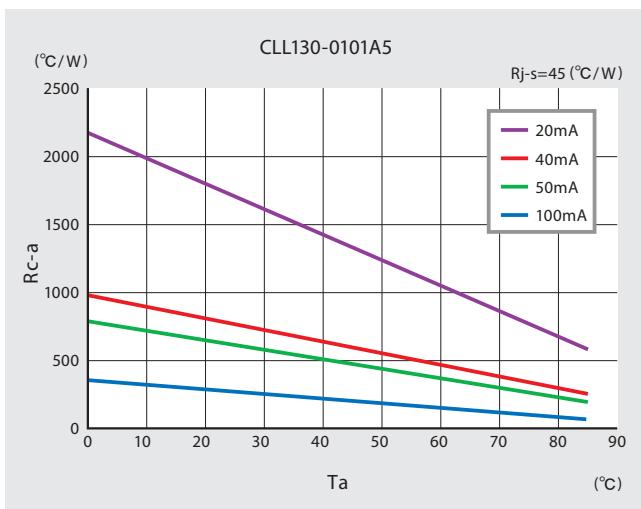
$$R_{s-a} = -T_a / P_d + T_j / P_d - R_{j-s}$$

and it is a straight line with the slope of $-1 / P_d$ and the intercept of $T_j / P_d - R_{j-s}$.

Figure-2 is the chart showing the relationship between the ambient temperature T_a and the thermal resistance

outside the package R_{s-a} indicated by driving current, where T_j is assumed to be 120°C - the absolute maximum rating value in the specifications for the CLL130 package. The higher the ambient temperature T_a and the larger the driving current, the smaller the allowable thermal resistance outside the package $R_{s-a} = R_s + R_e$. In brief, the external heat dissipation mechanism with smaller thermal resistance (this means better heat dissipation) is required in order to keep T_j from exceeding 120°C, the absolute maximum rating in the specifications, if the ambient temperature becomes higher and/or the driving current is larger. Therefore, use Figure-2 as a guide when selecting the external heat dissipation parts, and ultimately conduct thermal verification on actual devices.

Figure-2 T_a - R_{s-a}



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